PCN Number:	20140523000A		PCN Date:	07/01/2014
Title:	Qualification of Reduced Wire Bond diameter for the Family of Discrete Clip & Power Block Devices			
Customer Contact:	PCN Manager	Phone: +1(214)480-6037	Dept:	Quality Services
Proposed 1st Ship Date:	10/01/2014	Estimated Sample Availability:		Date provided upon request

Change Type:

☐	Assembly Site	☐	Assembly Process	☒	Assembly Materials
☐	Design	☐	Electrical Specification	☐	Mechanical Specification
☐	Test Site	☐	Packing/Shipping/Labeling	☐	Test Process
☐	Wafer Bump Site	☐	Wafer Bump Material	☐	Wafer Bump Process
☐	Wafer Fab Site	☐	Wafer Fab Materials	☐	Wafer Fab Process
		☐	Part number change		

PCN Details

Description of Change:

Revision A is to announce the addition of new devices that were not included on the original PCN notification. These new devices are highlighted and **bolded** in the device list below. The expected first shipment date for these new devices will be 90 days from this notice for these newly added devices only.

Texas Instruments is pleased to announce the qualification a reduced bond wire diameter for the family of Discrete Clip & Power Block Devices:

	Current	New
Bond Wire/Diameter	Au, 2.0 mil	**Au, 1.0 mil**

Reason for Change:

Continuity of Supply

Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):

None

Changes to product identification resulting from this PCN:

None

Product Affected

CSD16321Q5	CSD16408Q5	CSD17556Q5B	CSD58865Q5D
CSD16321Q5C	**CSD16408Q5C**	CSD17559Q5	CSD58867Q3D
CSD16322Q5	CSD16409Q3	CSD17566Q3	CSD58869Q5D
CSD16322Q5C	CSD16411Q3	CSD17570Q5B	CSD58870Q5D
CSD16323Q3	CSD16414Q5	CSD17573Q5B	CSD86330Q3D
CSD16323Q3C	CSD16415Q5	CSD17575Q3	CSD86350Q5D
CSD16325Q5	CSD16515Q5	CSD17576Q5B	CSD86360Q5D
CSD16325Q5C	CSD16556Q5B	CSD17590Q5B	CSD87330Q3D
CSD16327Q3	CSD16570Q5B	CSD18502Q5B	CSD87331Q3D
CSD16340Q3	CSD17303Q5	CSD18509Q5B	CSD87333Q3D
CSD16341Q5	CSD17304Q3	CSD18532NQ5B	CSD87350Q5D
CSD16350Q5	CSD17308Q3	CSD18532Q5B	CSD87351Q5D

CSD16401Q5	CSD17309Q3	CSD18540Q5B	CSD87351ZQ5D
CSD16406Q3	CSD17311Q5	CSD19502Q5B	CSD87352Q5D
CSD16407Q5	CSD17312Q5	CSD19532Q5B	CSD87353Q5D
CSD16407Q5C			

Qualification Data – Approved May, 2014

This qualification has been specifically developed for the validation of this change. The qualification data validates that the proposed change meets the applicable released technical specifications.

Reference Qualification# 1 : CSD87331Q3D (MSL 1-260C)

Package Construction Details

Assembly Site:	PAC	Mold Compound:	SID#200805
# Pins-Designator, Family:	8-DQZ, LSON-CLIP	Mount Solder:	SID#200757
Lead frame (Finish, Base):	Matte Sn, Cu	Bond Wire:	1.0 Mil Dia., Au

Qualification: ☐ **Plan**   ☒ **Test Results**

Reliability Test	Conditions	Sample Size/Fail
**T/C -40C/125C	-40C/+125C (500 Cyc)	77/0
Notes **- Preconditioning sequence: Level 1-260C.		

Qualification Data – Approved May, 2014

This qualification has been specifically developed for the validation of this change. The qualification data validates that the proposed change meets the applicable released technical specifications.

Reference Qualification# 2 : CSD58869Q5D (MSL 1-260C)

Package Construction Details

Assembly Site:	PAC	Mold Compound:	SID#202828
# Pins-Designator, Family:	8-DQY, LSON-CLIP	Mount Solder:	SID#200757
Lead frame (Finish, Base):	Matte Sn, Cu	Bond Wire:	1.0 Mil Dia., Au

Qualification: ☐ **Plan**   ☒ **Test Results**

Reliability Test	Conditions	Sample Size/Fail
**T/C -40C/125C	-40C/+125C (500 Cyc)	77/0
Notes **- Preconditioning sequence: Level 1-260C.		

Qualification Data – Approved May, 2014

This qualification has been specifically developed for the validation of this change. The qualification data validates that the proposed change meets the applicable released technical specifications.

Reference Qualification# 3 : CSD16407Q5 (MSL 1-260C)

Package Construction Details

Assembly Site:	PAC	Mold Compound:	SID#202828
# Pins-Designator, Family:	8-DQH, LSON-CLIP	Mount Solder:	SID#200757
Lead frame (Finish, Base):	Matte Sn, Cu	Bond Wire:	1.0 Mil Dia., Au

Qualification: ☐ **Plan**   ☒ **Test Results**

Reliability Test	Conditions	Sample Size/Fail
**T/C -40C/125C	-40C/+125C (500 Cyc)	77/0
Notes **- Preconditioning sequence: Level 1-260C.		

Qualification Data – Approved May, 2014			
This qualification has been specifically developed for the validation of this change. The qualification data validates that the proposed change meets the applicable released technical specifications.			
Reference Qualification# 4 : CSD25401Q3 (MSL 1-260C)			
Package Construction Details			
Assembly Site:	PAC	Mold Compound:	SID#202828
# Pins-Designator, Family:	8-DQG, LSON-CLIP	Mount Solder:	SID#200757
Lead frame (Finish, Base):	Matte Sn, Cu	Bond Wire:	1.0 Mil Dia., Au
Qualification: ☐ **Plan** ☒ **Test Results**			
Reliability Test	Conditions		Sample Size/Fail
**T/C -40C/125C	-40C/+125C (500 Cyc)		77/0
Notes **- Preconditioning sequence: Level 1-260C.			

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com